



Product Summary

V _{(BR)DSS}	RDS(on) max	I _D T _A = +25°C
-30V	8mΩ @ VGs = -10V	-17A
	10.2mΩ @ V _{GS} = -4.5V	-14.5A

Description

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- Power Management Functions
- Backlighting

Notes:

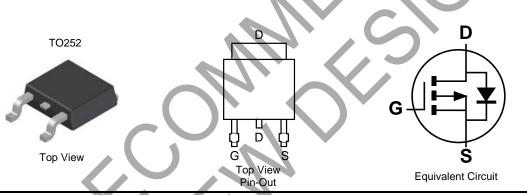
P-CHANNEL ENHANCEMENT MODE MOSFET

Features and Benefits

- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish—Tin Finish annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208@3
- Weight: 0.33 grams (approximate)



Ordering Information (Note 4 & 5)

Part Number	Compliance	Case	Packaging
DMP3010LK3-13	Standard	TO252	2500/Tape & Reel
DMP3010LK3Q-13	Automotive	TO252	2500/Tape & Reel

1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and

Lead-free. 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and

Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and
 < 1000ppm antimony compounds.</p>
 Automotive products are AEC-Q10x qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the

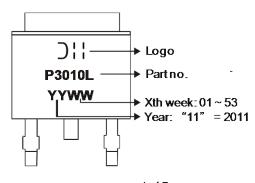
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 Automotive products are AEC-Q10x qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to https://www.diodes.com/quality/.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information





Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage			V _{DSS}	-30	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 7) V _{GS} = -10V	Steady State	T _A = +25°C T _A = +70°C	ID	-17.0 -13.0	А
	t<10s	T _A = +25°C T _A = +70°C	ID	-27.0 -21.0	А
Continuous Drain Current (Note 7) V_{GS} = -4.5V	Steady State	T _A = +25°C T _A = +70°C	ID	-14.5 -11.5	А
	t<10s $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$		ID	-23.0 -18.0	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	-100	А		
Maximum Body Diode Forward Current (Note 7)			Is	5.5	А
Avalanche Current (Note 8)			las	47	А
Avalanche Energy (Note 8)			E _{AS}	113	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 6)		Po	1.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state		72	°C/W
	t<10s	R _{0JA}	29	°C/W
Total Power Dissipation (Note 7)		PD	3.4	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady state		37	°C/W
merma Resistance, Junction to Ambient (Note 7)	t<10s	R _θ JA	15	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Tun	Max	Unit	Test Condition
	Symbol	IVIIO	Тур	wax	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV _{DSS}	-30		—	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	IDSS			-1	μA	$V_{DS} = -30V, V_{GS} = 0V$
Gate-Source Leakage	Igss		_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	V _{GS(th)}	-1.1	-1.6	-2.1	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance		_	6.5	8		$V_{GS} = -10V, I_D = -10A$
Static Drain-Source On-Resistance	RDS (ON)	—	7.2	10.2	mΩ	$V_{GS} = -4.5V, I_D = -10A$
Forward Transfer Admittance	Y _{fs}	_	30	—	S	$V_{DS} = -15V, I_D = -10A$
Diode Forward Voltage	V _{SD}	_	-0.65	-1.0	V	$V_{GS} = 0V, I_{S} = -1A$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	Ciss		6234			$V_{DS} = 15V, V_{GS} = 0V$ f = 1.0MHz
Output Capacitance	Coss	—	1500	—	pF	
Reverse Transfer Capacitance	Crss	_	774	—		T = T.000172
Gate Resistance	R _G	_	1.28	—	μ	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge	Qg	_	59.2	—		
Gate-Source Charge	Q _{gs}	_	16.1	—	nC	$V_{DS} = -15V, V_{GS} = -4.5V,$ $I_{D} = -10A$
Gate-Drain Charge	Q _{gd}	_	15.7	—		
Turn-On Delay Time	t _{D(on)}	_	11.4	_		
Turn-On Rise Time	tr		9.4	_	n 0	$V_{DS} = -15V, V_{GEN} = -10V,$
Turn-Off Delay Time	t _{D(off)}		260.7	_	ns	$R_G = 6\Omega, I_D = -1A$
Turn-Off Fall Time	tf	_	99.3	_		

Notes:

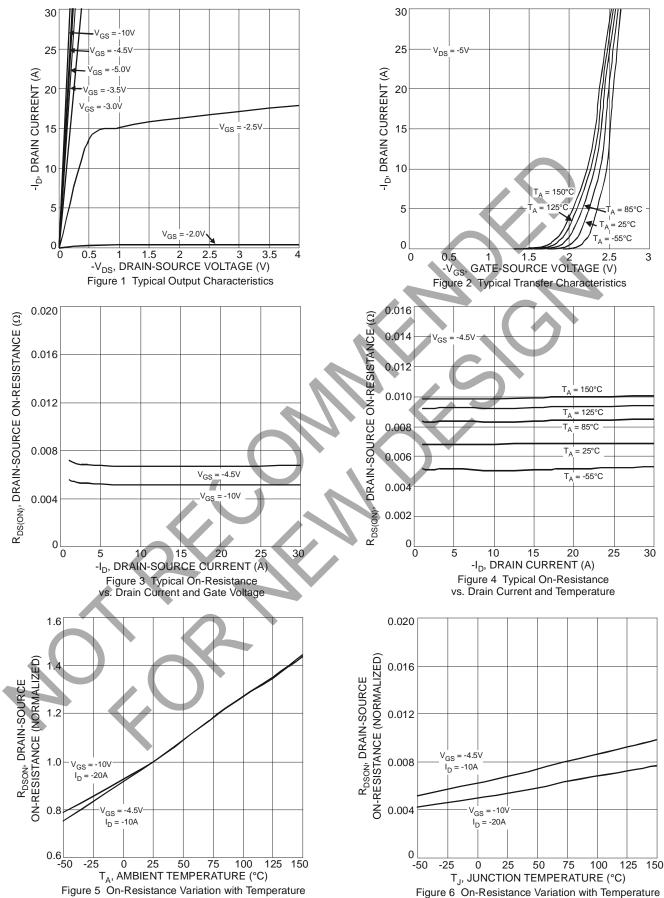
6. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
7. Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
8. UIS in production with L = 0.1mH, T_J = +25°C.

9. Short duration pulse test used to minimize self-heating effect.

10. Guaranteed by design. Not subject to production testing.

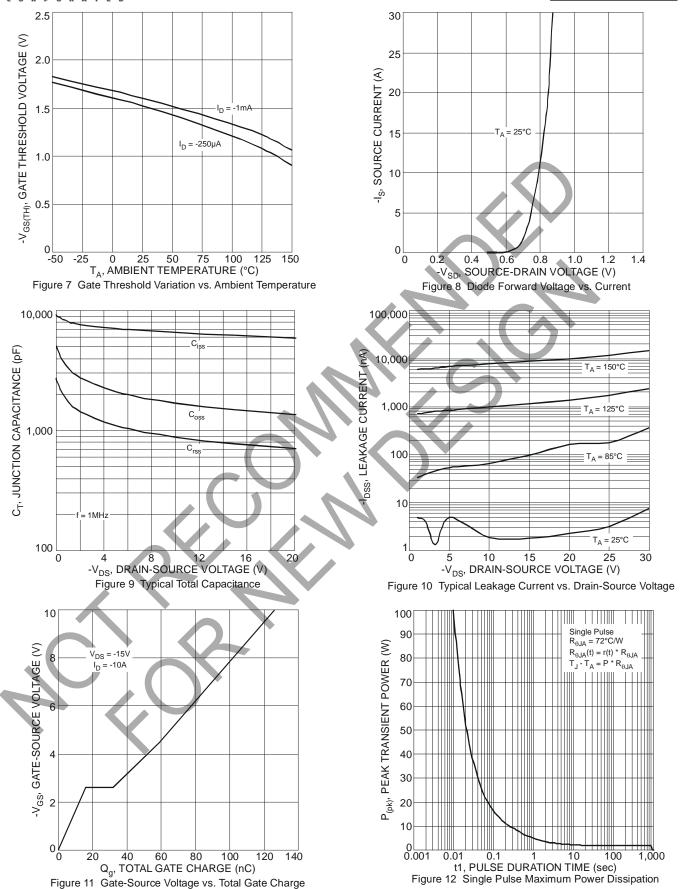


DMP3010LK3

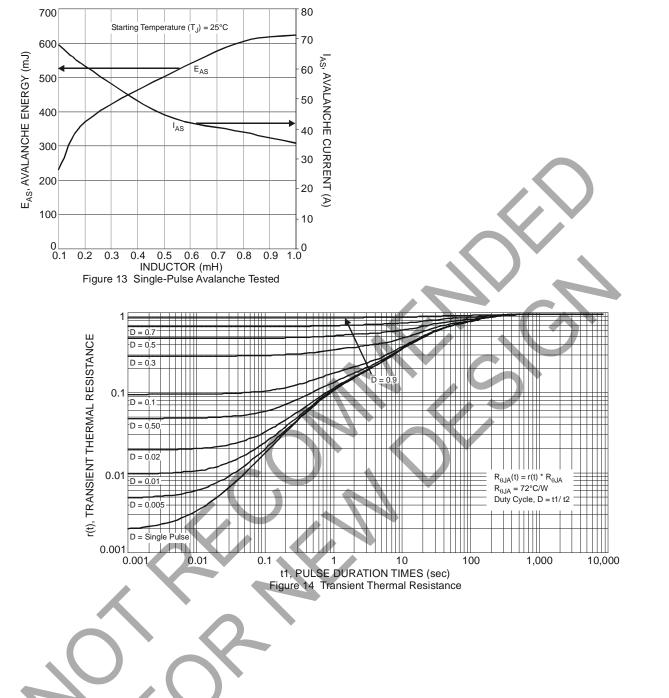




DMP3010LK3



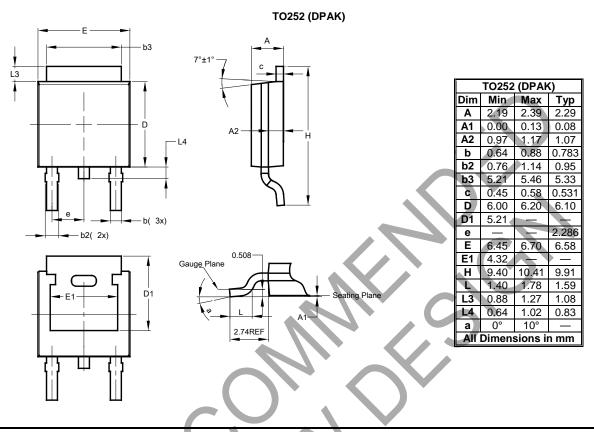






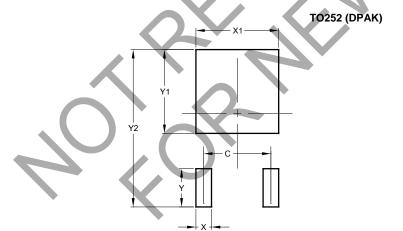
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



Suggested Pad Layout

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Dimensions	Value (in mm)			
С	4.572			
Х	1.060			
X1	5.632			
Y	2.600			
Y1	5.700			
Y2	10.700			



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